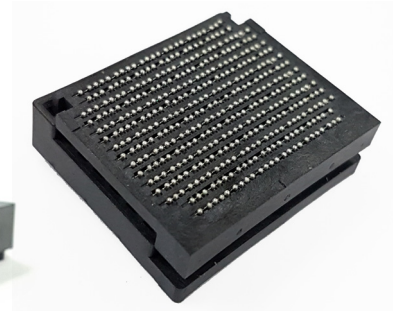
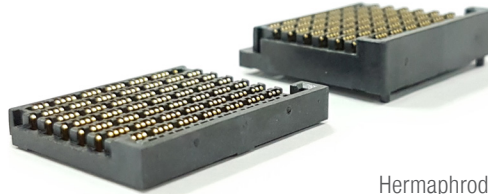


# Mirror Mezz Connectors



**Footprint-compatible Hermaphroditic Mirror Mezz connector lowers application costs with stackable mating to support data speeds up to 56 Gbps per differential pair for telecommunications, networking and other applications**

## Features and Benefits

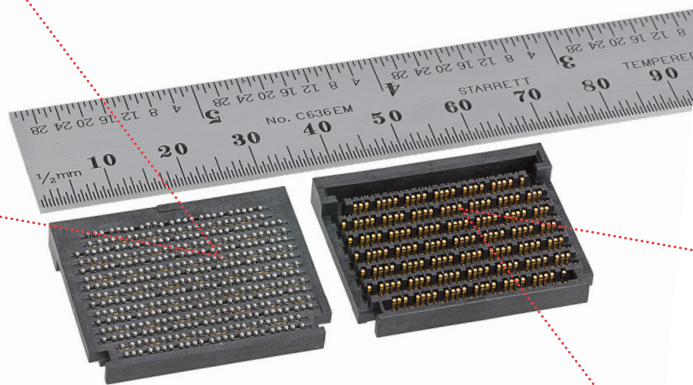


Hermaphroditic Mirror Mezz Connectors in 2.50 and 5.50mm (prototype only) height configurations (Remark: Picture on the right shows a 2.50mm connector mated to the 5.50mm version)



### Stitched BGA design

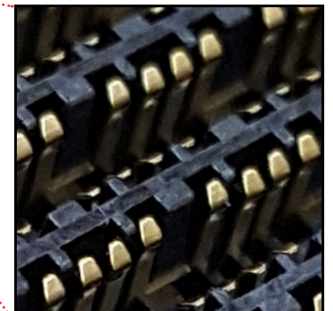
Offers more cost savings than insert-molded BGA attachments. Stitched contact structure reduces lead-times and the connector design allows for simplified product matrix



Bottom (left) and top-side (right) perspectives of the 2.50mm height Mirror Mezz Connector

### Intricately designed terminal structure

Provides numerous mechanical strengths while also benefiting from cutting-edge electrical features for some of the faster speeds in the industry



## Applications

### Data/Computing

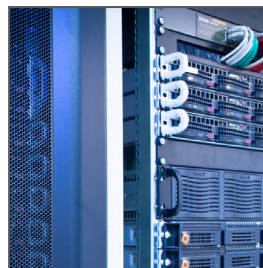
- Server
- Networking
- Storage

### Telecommunications/Networking

- Infrastructure
- Networking



Storage



Networking

## Specifications

### REFERENCE INFORMATION

Reference Information  
Packaging: Tape and Reel  
Mates With: 2.50 and 5.50mm height connectors  
can self- or cross-mate.  
Designed In: Millimeters  
RoHS: Yes  
Halogen Free: Yes  
Glow Wire Compliant: NA

### ELECTRICAL

Voltage (max.): 30V AC  
Current (max.): 1A per contact  
Low Level Contact Resistance (max. initial):  
30 milliohm for 5mm stack height  
Dielectric Withstanding Voltage: 500V DC  
Insulation Resistance: 1000 Megohm  
Impedance: 92 ohms

### MECHANICAL

Average Mating Force: 0.5N per pin (max.)  
Unmating Force: 0.045N per pin (min.)  
Contact Normal Force (min.): 0.2N per pin  
Durability (max.): 100 cycles

### PHYSICAL

Housing: High Temperature Thermoplastic, UL94-V0  
Contact: High Performance Copper Alloy  
Plating: Selective Gold  
Contact Area — 0.76 micron Gold (Au)  
Solder Tail Area — 2.54 micron Tin (Sn)  
Underplating — 1.27 micron Nickel (Ni)  
Operating Temperature: -55 to 105°C

## Ordering Information

Series No.	No. of rows	No. of differential pairs per row in Zone 1, 2 and 3	Total No. of differential pairs (excluding orphan pair)	Total No. of orphan pairs	Dimension
202828			Refer to Sales Drawings		